電磁兼容原理與設計

話題：我擁有的EMC，EMI，可靠度方面的資料我擁有的EMC，EMI，可靠度方面的資料我將陸續上傳。
聯繫模式：QQ：16322127（可透過QQ索取，要標注EMC，EMI，可靠度字樣）

電磁兼容原理與設計（基礎知識）
Digital Signal Integrity-Modeling and Simulation with Interconnects and Package
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EMC技術介紹
EMC技術介紹
EMC設計技術
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High-speed Digital Design - Johnson & Graham
High-Speed Digital System Design
PCB上信號線產生的電磁頻譜
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避免混合訊號系統的設計陷阱
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單片機系統常用軟體抗干擾措施
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開關電源的抗干擾問題
讓我們一起認識手機輻射
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//Reliability Review of North American Gas/Electric System Interdependency
//Semiconductor Device Reliability Failure Models
//accelerated testing
//Avoiding Vibration in Odd-Shaped Printed-Circuit Boards
//Better Accelerated Tests

//HALT AND HASS ON THE VOICEMEMO
//Combining Moments of Inertia
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//Designing Electronics for High Vibration and Shock
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//HASS DEVELOPMENT METHODOLOGY HOW TO DEVELOP A SCREEN,WHEN TO CHANGE A SCREEN, AND WHEN TO RE-PROVE A SCREEN
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//IBM consulting-Becoming A Process Based Organization
//IBM演示技巧教程
//MTBF Report_13 October 04
//MTBF_Paper
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//An Extended Reliability Growth Model For Managing And Assessing Corrective Actions
//Reliability Monitor Report
//reliability tools and integration in the manufacting phase
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//Reliability_Mathematics
//reliability-pricing-model-overview
//rr_ed_fault_risk_reduction
//software_reliability_measurement or Life Cycle Core Knowledge Requirements for Software Reliability Measurement
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//THERMAL AND VIBRATION ISOLATION TECHNIQUES FOR HARD DRIVES AND PCI CARDS
//Reliability, Availability, and Operability
//PROBABILISTIC ENGINEERING DESIGN

//Where Is My Data For Making Reliability Improvements
//可靠性技術的應用與發展
//蒙特卡羅法在零件可靠性設計中的應用
//Failure Mode and Effects Analysis (FMEA) A Guide for Continuous Improvement for the Semiconductor Equipment Industry
//Automatic FMEA
//Representation of Functional Relations among Parts and Its Application to Product Failure Reasoning
//Design FMEA
//FAILURE MODE AND EFFECTS ANALYSIS (FMEA)
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//TOOLS OF RELIABILITY ANALYSIS -- Introduction and FMEAs
//nasa fmea bibliography
//Philips FMEA English
//An Introduction to Risk/Hazard Analysis for Medical Devices
//Using Failure Mode Effect Analysis (FMEA) to Improve Service Quality Service Operations Management
//QUANTIFIED RISK ASSESSMENT TECHNIQUES (PART 1)
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//Scenario-based FMEA
//PROCESS HAZARD ANALYSIS
//software fmea
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//Procedures for Assessing Risks
//Incorporating a user-focused failure modes
//DACTRON控制單元　介
//包　落下　　介
//　　介
//　磁式高　振
//　境　力　　振　　介
//　　室英文　　料
//　　室中文　　料
//　　型低　振
//　　型低　振
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//Vht_C真空乾燥箱
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//英國華萊氏公司產品瀏覽
//BioLine V3.0_C_2003植物生長試驗箱
//Company Presentation V3.0_C_2003德國富奇介紹
//Human Performance Testing V3.0_C_2003人體資源測試
//IEC60068-3-5溫度變化率
//IP-Overview_C工業防護
//Pharma V3.0_C_2003製藥工業的藥品穩定性試驗
//SC_C_2003陽光類比試驗箱
//Thermalshock_C_2003溫度衝擊試驗箱
//V . T S C H - Climatic Test Cabinet 德國富奇公司-氣候試驗箱VC4018C
//VP_C_2003藥物穩定性試驗
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//Vtsvcs_C_2003快速溫度變化試驗箱
//Vtvc_detail_C_2003高低溫試驗箱
//Vtvvcv_C_2003振動和更多的……
//WALK_IN_APP步入式試驗室
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//LIFETME CALCULATION FORMULA OF ALUMINUM ELECTROLYTIC CAPACITORS

//Guide to Use Aluminum Electrolytic Capacitors
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//Accelerated_Standards_Transition_Plan_Approved_by_Board_06_04
//Accelerated stress testing
//the enviromental stress screen handbook
//Pre halt analysis
//談加速壽命試驗
//2003 CARTS Derating differences Ta-KO-AO
//sony ss-00259 handbook
//ADI Reliability Handbook
//stress test qualification for discrete semiconductors
//An Overview of Weibull Analysis
//balloons reliability analysis
//An Improved SPICE Capacitor Model
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//IEC 60950
//Improving the Performance of Your Root Cause Analysis (RCA) Program
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//Dynamic reliability and risk assessment of the accident localization system of the Ignalina NPP RBMK-1500 reactor
//Semiconductor Device Reliability Failure Models
//Software Reliability Handbook Chaper11
//SONY SS-00259-1第四版(英日)
//SONY00254-5-R4
//Standard Linear IC reliability
//Stress test Qualification for Integrated Circuits
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//ACPI Component Architecture Programmer Reference
//A critique of the EMC Directive

//Abatement of Static Electricity
//An EMC Directive for the Next Century
//COMPLIANCE SYSTEMS CORPORATION app_note_EN61000-4-5
//Australian EMC Regulation and Routes to Compliance
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//Advanced Battery Engineering Facility
//An Analysis and Performance Evaluation of a Passive Filter Design Technique for Charge Pump PLL’s AN-1001
//Introduction to Power Supplies
//Don"t Throw Away Those Batteries!
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//Uncertainty_Analysis Thunder Scientific
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//Chamber Study
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//加速試驗
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//溫度試驗中斷處理的依據

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//2002年度《RAMS》論文目錄
//國外CALS近期發展動態綜述
//國外CALS近期發展的三個新特點
//CSP封裝產品在熱應力循環條件下的可靠性分析
//環境應力篩選（ESS）
//ESS
//ESS_Fixture
//《通信設備可靠性通用試驗方法》YD/T 282-2000行業標準介紹
//GJB150_19
//HALT& HASS
//國際電工委員會IEC/TC56（可信性技術委員會）頒發的"可信性"國際標準
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//Improper_ESS_part_2
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//Managing Reliability and Maintainability (R&M)
//quality and reliability
//reliability develop
//reliability training
//以可靠性爲中心的維修發展動態
//SAE RCM標準的製訂背景
//Software Support Life Cycle Process Evaluation Guide
//測試污染對測試結果的影響
//測試技術要滿足工程項目需求
//Audit Report AA 00-341 High Level Architecture
//Audit Report AA 01-128 Integrated System Control
//Audit Report AA 01-23 Simulation High Level Architecture
//Managing Reliability and Maintainability
//Guidance on in-Service Reliability and Maintainability (R&M)
//Intraoperability and Interoperability of Marine Corps Tactical C4I Systems
//AF Instruction 33-133 Joint Technical Architecture -- Air Force
//Promulgation of DOD Policy For Assessment, Test, and Evaluation of Information Technology System Interoperability

//Compatibility, Interoperability, and Integration of Command, Control, Communications, and Computer (C4) Systems
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FMEA
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//failure analysis of semiconductor devices
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//FMEA Analysis Guidelines
//潛在失效模式及后果分析
//TOOLS OF RELIABILITY ANALYSIS -- Introduction and FMEAs
//FMEA2
//FMEA3
//FMEA失效模式和效果分析
//how to selling_root_cause to management
//Philips FMEA
//Potential Failure Mode and Effects Analysis
//Random-Failure-Models
/ROOT CAUSE ANALYSIS
//root causea nalysis chapter1
//SURFACE VEHICLE RECOMMENDED PRACTICE
//WHAT MAKES A ROOT CAUSE FAILURE ANALYSIS PROGRAM SUCCESSFUL
//故障模式影響分析
//如何　行失效模式　影　分析

ESD
//Digital Phosphor Oscilloscopes
//A Safety Standard for Electrosensitive Protective Equipment
//Adding Value through Accredited Testing
//Littelfuse Cable Protectors for High Current Applications
//CMOS積體電路的ESD設計技術
//computer ESD solution
//Fundamentals of Electrostatic Discharge An Introduction to ESD
//ESD Suppression Technologies
//ESD Suppression Technologies ec622a ec622a

//Selecting an ESD Suppressor
//ESD Protection Audio Input and Output Lines
//Capacitance and Signal Integrity
//ESD Protection Digital Visual Interface Data Lines
//ESD Protection IEEE 1394 Data Lines
//ESD Protection USB 1.1 Data Lines
//ESD Protection USB 2.0 Data Lines
//ESD Protection Video Input and Output Lines
//General Purpose ESD Protection
//ESD Journal - The ESD & Electrostatics Magazine
//ESD protect
//ESD Standards
//Evaluation of Materials for Cleanliness and ESD Protective Properties
//Electrostatic Discharge (ESD) in Magnetic Recording Past, Present and Future
//Explosions and ESD
//From Electrostatics to ESD
//Fuse fact
//Ground planes for low cost boards
//Grounding Strategies for Printed Circuit Boards
//How Is Static Electricity Generated
//Is Static Electricity Static
//Littelfuse Resistors for Voltage Suppression
//SiVa ESD Demo
//The Competitive Advantage of Standards
//The Evolution of Guide into ISO 17025
//What It Means to ESD

HALT
//ENVIRONMENTAL EFFECTS
//筆記本電腦失效模式分析表
//測試前筆記本性能測試
//測試前后的機構電性功能驗証
//常見失效模式一覽表
//可靠性驗証測試
//失效分析是指研究產品潛在的或顯在的失效機理
//失效效應危害度一覽表
//ENVIRONMENTAL ENGINEERING CONSIDERATIONS AND LABORATORY TESTS
//A fundamental overview of accelerated-testing analytic models
//A5 P-FMEA
//accelerated and classical reliability methods integrated
//accelerated model

//accelerated test reference1
//accelerated test reference2
//accelerated test reference3
//accelerated test reference4
//美國可靠性強化試驗技術發展點評
//An approach to designing accelerated life-testing experiments
//Ast
//BCC-4V Halt Test
//Critical Analysis Team Report on Accelerated Waste Retrieval Final Design and Fixed Price Contracting
//Don't Let the Cost of HALT Stop You
//電子設備的可靠性設計技術
//FEMMA Technology Overview FEMMA Technology Overview
/fixturing China presentation 2-04
//FMEA5
//HALT & HASS1
//HALT GUIDELINE 2004
//HALT Guideline
//HALT HASS SEMINAR PRESENTED BY ENVIROTRONICS
//The Application of HALT for Increased Product Reliability
//加速試驗綜述
//HALT&HASS基礎篇 - 中文 - 2003
//HALT-HASS
//HALT-Testing With a Different Purpose
//Hass and Halt
//HASS of Products With Very Low Failure Rates
//high reliability challenge of broadband equipment
//Highly Accelerated Life Testing
//緊湊型節能燈壽命的常規試驗方法
//Material failure mechanisms and damage models
//MTBF Assurance test
//PCB relia design
//Quick guide Accelerated Life Testing Data Analysis Basics
//quick guide life data analysis
//可靠性設計
//Reliability Glossary
//reliability prediction VS HALT testing
//Searching for appropriate humidity accelerated migration reliability tests methods
//System reliability modeling considering the dependence of component environmental influences
//understanding accelerated life testing analysis

//what is HAST testing
//why HALT cannot produce a meaningful MTBF number and why this should not be concern
//高加速壽命試驗(HALT)與高加速應力篩選(HASS)
//失效率
//用高壓鍋做測試

//統計知識
//機率與統計入門
研究。
//Pipe Wall Thickness Decisions Using Weibull Analysis
//Weibull analysis for production data
//Weibull Analysis of Production Data
//方差分析(1)
//方差分析(2)
//機率統計
//高級基本統計
//質量管理中的技術統計

pcb
//BGA技術與質量控制
//Creep of Pb of Pb-free Solders free Solders
//intel glossary
//High Speed Board Design
//LEAD-FREE MANDATE PLUMBS NEW DESIGN CHALLENGES
//印製電路板設計原則和抗干擾措施
//PCB化學鍍鎳金工藝介紹
//SMT technology
//電子工業的絲網印刷
//電子裝聯焊接技術現狀與課題
//混合信號電路板的設計準則
//局部焊接的應用
//無鉛焊料的開發與應用
//新手上路認識PCB
//印製電路板的可靠性設計措施
//印製電路工藝創新探討

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//ATMEL可靠性報告
/MICROCHIP的可靠性報告
//Software Fault Tolerance

//高加速壽命試驗（HALT）與高加速應力篩選（HASS）
//論加速試驗
//HDBK-HALT-HASS
//LeCroy數字示波器操作手冊
//MTBF
//thermal module design
//散熱設計準則
//Vedio & Sound Technology
//振動測試概論
//Vibration Technology
//振動技術簡介
//An Overview of Vehicle Pass-by Noise
//Time Domain Acoustical Holography and Its Applications
//Key Steps and Methods in the Development of Low Noise Engines
//Squeak and Rattle　State of the Art and Beyond
//Changing the Effective Mass to Control Resonance Problems
//Torsional Resonance Analysis in Air Handling Units
//Understanding the Physics of Electrodynamic Shaker Performance
//An Overview of Vehicle Pass-by Noise
//Newtonian Physics
//Conservation Laws
//Electricity and Magnetism
//Building Vibration Can Contaminate Clean Factories, Cleanrooms And Clean Activitie
//cots vibration testing
//Do We Know What We Are Doing
//Drop Tests vs Shock Table Transportation Tests
//Dynamic design
//Experimental Modal Analysis
//LASER ALIGNMENT SPECIFICATION FOR NEW AND REBUILT MACHINERY, EQUIPMENT AND COMPONENTS
//GENERAL MOTORS CORPORATION VIBRATION STANDARD
//Going To Witness A Vibration Test
//Going To Witness A Vibration Test
//Guidelines for Jury Evaluations of Automotive Sounds
//King Design Test Specification 1.2
//Mechanical Waves
//Newtonian Physics
//FedEx Package_Testing_Procedures
//PSD pattern 及 total Grms 值的　算
//Refraction of Sound Waves
//Rotational_Shock

//shock test system
//Squeak and Rattle　State of the Art and Beyond
//The Dynamic Vibration Absorber
//The Politics of Accelerated stress testing
//Time Domain Acoustical Holography and Its Applications
//Torsional Resonance Analysis in Air Handling Units
//Understanding the Physics of Electrodynamic Shaker Performance
//vibration test detail
//Vibration
//Vibrations and Wave
//包裝設計基礎
//包裝試驗
//多軸振動環境試驗技術
//海軍製造篩選程式
//可靠性振動基礎
//中高量級衝擊試驗技術
//weibull的有關問題(共30份)
//BGA可靠性表征項目：溫度循環試驗
/ESD損傷實例
//半導體分立器件的可靠性設計
//半導體積體電路的可靠性設計
//半導體器件失效原因分析
//當代質量觀與可靠性
//電氣繼電器(第20部分保護系統)
//電容器的可靠性設計
//電子元器件的防靜電應用
//電子元器件的防浪涌應用
//電子元器件的防噪聲應用
//電子元器件的抗輻射應用
//電子元器件的可靠性安裝
//電子元器件的選擇和應用
//電子元器件的質量與可靠性軍用標準體系
//電子元器件電路佈局的可靠性設計
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//電阻器的使用問題
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//方案階段
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//概述
//矽可控整流器（SCR）的使用問題
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//環境加速試驗的條件
//基本概念二
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//計算機輔助可靠性評價技術
//可靠性工程技術現狀2001年報告
//可靠性工作主要內容
//可靠性技術講座(下)
//可靠性篩選
//微電路的型號命名和採買
//微電路的選用原則
//微電路的質量、可靠性等級
//微電路降額設計指南
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//元器件優選目錄編製要求
//35 MAINTENANCE AUDITS
//FAILURES AND ERRORS
//A Metric for Focusing Reliability Efforts
//AN OVERVIEW OF WEIBULL Chpt1
//ASTM_testing
//Availability and Reliability
//Ball-Bearing-Data-by-Lieblein-and-Zelan
//basic of oil analysis
//business centered maintenance
//Project Management Professional Certification Handbook 03-2002
//Changing_your_organization_for_better1
//Changing_your_organization_for_better2
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//Changing_your_organization_for_better4
//Changing_your_organization_for_better5
//Cost Of Unreliability
//Cost_Effective_Calibration
//定義必要的可靠性
//Distribution & Logistics Strategy
//Establishing a sense of urgency
//執行測試
//Heat Exchanger IRIS Wall Thickness And Gumbel Smallest Distribution
//How To Justify Equipment Improvements Using
//Integrated Service Technology

//Key_Performance_Indicators
//manufacturing and business excellence
//maximizing_maintenance_profits
//micro reliability and lifetime estimation
//Moving from a Repair focused to a Reliability focused Culture
//Moving from a Repair-focused to a Reliability-focused Culture
//MTBF for notebook
//notebook test Plan
//OCE
//Predict Future Failures From Your Maintenance Records
//REDUCING THE COST OF PREVENTIVE MAINTENANCE
//reliability glossary
//Reliability STD
//Reliabilty and dependability standards are described
//ROHS E文版
//ROHS中文版
//Comparison of Reliability-Availability Mission Simulators
//Small Sample Size Datasets Help or Hindrance
//Solder Data Practice Guide
//SONY STANDARD SS-00259 中英文版
//VIII. STANDARDS AND QUALITY CERTIFICATION FOR QUALITY SYSTEMS,SAFETY, ANDRELIABILITY OF SEMICONDUCTOR DEVICES
//statistical investigation of fatigue life of deep-groove ball bearings
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//　子　品製造防　　范
//美國可靠性工程試題集
//威布爾分佈壽命分析
//晶片驗証測試及失效分析

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